

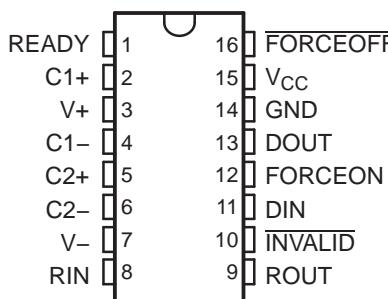
## FEATURES

- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operates With 3-V to 5.5-V  $V_{CC}$  Supply
- Operates at Least 1 Mbit/s
- Low Standby Current . . . 1  $\mu$ A Typ
- External Capacitors . . .  $4 \times 0.1 \mu$ F
- Accepts 5-V Logic Input With 3.3-V Supply
- Designed to Be Interchangeable With industry Standard '3227 Devices
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection for RS-232 I/O Pins
  - $\pm 15$  kV – Human-Body Model
  - $\pm 8$  kV – IEC61000-4-2, Contact Discharge
  - $\pm 8$  kV – IEC61000-4-2, Air-Gap Discharge
- Auto-Powerdown Plus Feature Automatically Disables Drivers for Power Savings
- Packaged in Plastic Shrink Small-Outline Package

## APPLICATIONS

- Battery-Powered, Hand-Held, and Portable Equipment
- PDAs and Palmtop PCs
- Notebooks, Sub-Notebooks, and Laptops
- Digital Cameras
- Mobile Phones and Wireless Devices

DB PACKAGE  
(TOP VIEW)



## DESCRIPTION/ORDERING INFORMATION

The TRS3227 consists of one line driver, one line receiver, and a dual charge-pump circuit with  $\pm 15$ -kV ESD protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. This device operates at data-signaling rates of 1 Mbit/s in normal operating mode and a maximum of 30-V/ $\mu$ s driver output slew rate. This device also features a logic-level output (READY) that asserts when the charge pump is regulating and the device is ready to begin transmitting.

The TRS3227 achieves a 1- $\mu$ A supply current using the auto-powerdown plus feature. This device automatically enters a low-power powerdown mode when the RS-232 cable is disconnected or the drivers of the connected peripherals are inactive for more than 30 s. It turns on again when it senses a valid transition at any driver or receiver input. Auto-powerdown saves power without changes to the existing BIOS or operating system.

The TRS3227C is characterized for operation from 0°C to 70°C. The TRS3227I is characterized for operation from  $-40$ °C to 85°C.

## ORDERING INFORMATION

$T_A$	PACKAGE <sup>(1)(2)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	SSOP – DB	Reel of 2000	TRS3227CDBR
$-40$ °C to 85°C	SSOP – DB	Reel of 2000	TRS3227IDBR

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at [www.ti.com](http://www.ti.com).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

FUNCTION TABLE<sup>(1)</sup>

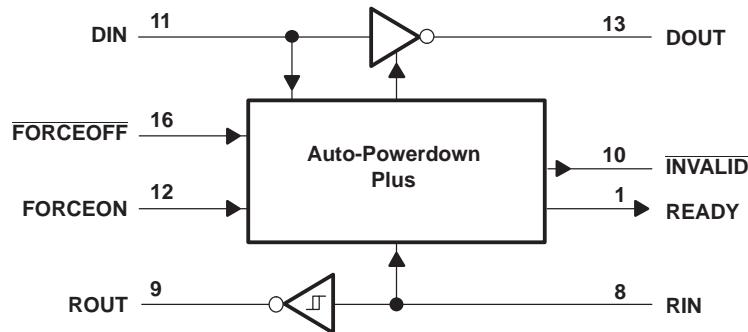
INPUT CONDITIONS				OUTPUT STATES				OPERATING MODE
FORCEON	FORCEOFF	RECEIVER OR DRIVER EDGE WITHIN 30 s	VALID RS-232 LEVEL PRESENT AT RECEIVER	DRIVER	RECEIVER	INVALID	READY	
Auto-Powerdown Plus Conditions								
H	H	NO	NO	Active	Active	L	H	Normal operation, auto-powerdown plus disabled
H	H	NO	YES	Active	Active	H	H	Normal operation, auto-powerdown plus disabled
L	H	YES	NO	Active	Active	L	H	Normal operation, auto-powerdown plus enabled
L	H	YES	YES	Active	Active	H	H	Normal operation, auto-powerdown plus enabled
L	H	NO	NO	Z	Active	L	L	Powerdown, auto-powerdown plus enabled
L	H	NO	YES	Z	Active	H	L	Powerdown, auto-powerdown plus enabled
X	L	X	NO	Z	Active	L	L	Manual powerdown
X	L	X	YES	Z	Active	H	L	Manual powerdown
Auto-Powerdown Conditions								
INVALID	INVALID	X	NO	Z	Active	L	L	Powerdown, auto-powerdown enabled
INVALID	INVALID	X	YES	Active	Active	H	H	Normal operation, auto-powerdown enabled

(1) H = high level, L = low level, X = irrelevant, Z = high impedance

### TERMINAL FUNCTIONS

TERMINAL		DESCRIPTION
NAME	NO.	
C1+	2	Positive terminal of voltage-doubler charge-pump capacitor
C1-	4	Negative terminal of voltage-doubler charge-pump capacitor
C2+	5	Positive terminal of inverting charge-pump capacitor
C2-	6	Negative terminal of inverting charge-pump capacitor
DIN	11	CMOS driver input
DOUT	13	RS-232 driver output
FORCEOFF	16	Force-off input, active low. Drive low to shut down drivers, receivers, and charge pump. This overrides auto-shutdown and FORCEON (see Function Table).
FORCEON	12	Force-on input, active high. Drive high to override powerdown, keeping drivers and receivers on (FORCEOFF must be high) (see Function Table).
GND	14	Ground
INVALID	10	Valid signal detector output, active low. A logic high indicates that a valid RS-232 level is present on a receiver input.
READY	1	Ready to transmit output, active high. READY is enabled high when V- goes below $-3.5\text{ V}$ and the device is ready to transmit.
RIN	8	RS-232 receiver input
ROUT	9	CMOS receiver output
V+	3	$+2 \times V_{CC}$ generated by the charge pump
V-	7	$-2 \times V_{CC}$ generated by the charge pump
V <sub>CC</sub>	15	3-V to 5.5-V single-supply voltage

### LOGIC DIAGRAM (POSITIVE LOGIC)



**Absolute Maximum Ratings<sup>(1)</sup>**

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CC}$	Supply voltage range <sup>(2)</sup>		-0.3	6	V
$V_+$	Positive output supply voltage range <sup>(2)</sup>		-0.3	7	V
$V_-$	Negative output supply voltage range <sup>(2)</sup>		0.3	-7	V
$V_+ - V_-$	Supply voltage difference <sup>(2)</sup>			13	V
$V_I$	Input voltage range	Driver (FORCEOFF, FORCEON)	-0.3	6	V
		Receiver	-25	25	
$V_O$	Output voltage range	Driver	-13.2	13.2	V
		Receiver (INVALID, READY)	-0.3	$V_{CC} + 0.3$	
	Short-circuit duration	DOUT to GND		Unlimited	
$\theta_{JA}$	Package thermal impedance <sup>(3)</sup>			82	°C/W
	Lead temperature 1.6 mm (1/16 in) from case for 10 s			260	°C
$T_{stg}$	Storage temperature range		-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltages are with respect to network GND.

(3) The package thermal impedance is calculated in accordance with JESD 51-7.

**Recommended Operating Conditions<sup>(1)</sup>**See [Figure 5](#)

			MIN	NOM	MAX	UNIT
Supply voltage		$V_{CC} = 3.3\text{ V}$	3	3.3	3.6	V
		$V_{CC} = 5\text{ V}$	4.5	5	5.5	
$V_{IH}$	Driver and control high-level input voltage	$V_{CC} = 3.3\text{ V}$	2		5.5	V
		$V_{CC} = 5\text{ V}$	2.4		5.5	
$V_{IL}$	Driver and control low-level input voltage	DIN, FORCEOFF, FORCEON	0	0.8		V
$V_I$	Receiver input voltage		-25	25		V
$T_A$	Operating free-air temperature	TRS3227C	0	70		°C
		TRS3227I	-40	85		

(1) Test conditions are  $C_1 - C_4 = 0.1\text{ }\mu\text{F}$  at  $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ ;  $C_1 = 0.047\text{ }\mu\text{F}$ ,  $C_2 - C_4 = 0.33\text{ }\mu\text{F}$  at  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ .

**Electrical Characteristics<sup>(1)</sup>**over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 5](#))

	PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	UNIT	
$I_I$	Input leakage current	FORCEOFF, FORCEON		$\pm 0.01$	$\pm 1$	$\mu\text{A}$	
$I_{CC}$	Supply current ( $T_A = 25^\circ\text{C}$ )	Auto-powerdown plus disabled	No load, FORCEOFF and FORCEON at $V_{CC}$		0.3	2	$\text{mA}$
		Powered off	No load, FORCEOFF at GND		1	10	
		Auto-powerdown plus enabled	No load, FORCEOFF at $V_{CC}$ , FORCEON at GND, All RIN are open or grounded		1	10	

(1) Test conditions are  $C_1 - C_4 = 0.1\text{ }\mu\text{F}$  at  $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ ;  $C_1 = 0.047\text{ }\mu\text{F}$ ,  $C_2 - C_4 = 0.33\text{ }\mu\text{F}$  at  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ .

(2) All typical values are at  $V_{CC} = 3.3\text{ V}$  or  $V_{CC} = 5\text{ V}$ , and  $T_A = 25^\circ\text{C}$ .

## DRIVER SECTION

### Electrical Characteristics<sup>(1)</sup>

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)  
 (see [Figure 1](#) and [Figure 2](#))

PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	UNIT
$V_{OH}$ High-level output voltage	DOUT at $R_L = 3\text{ k}\Omega$ to GND, DIN = GND	5	5.4		V
$V_{OL}$ Low-level output voltage	DOUT at $R_L = 3\text{ k}\Omega$ to GND, DIN = $V_{CC}$	-5	-5.4		V
$I_{IH}$ High-level input current	$V_I = V_{CC}$		$\pm 0.01$	$\pm 1$	$\mu\text{A}$
$I_{IL}$ Low-level input current	$V_I$ at GND		$\pm 0.01$	$\pm 1$	$\mu\text{A}$
$I_{OS}$ Short-circuit output current <sup>(3)</sup>	$V_{CC} = 3.6\text{ V}$ , $V_O = 0\text{ V}$		$\pm 35$	$\pm 60$	mA
	$V_{CC} = 5.5\text{ V}$ , $V_O = 0\text{ V}$		$\pm 35$	$\pm 60$	
$r_o$ Output resistance	$V_{CC}$ , $V_+$ , and $V_- = 0\text{ V}$ , $V_O = \pm 2\text{ V}$	300	10M		$\Omega$
$I_{off}$ Output leakage current	FORCEOFF = GND, $V_O = \pm 12\text{ V}$ , $V_{CC} = 0$ to $5.5\text{ V}$			$\pm 25$	$\mu\text{A}$

(1) Test conditions are  $C1\text{--}C4 = 0.1\text{ }\mu\text{F}$  at  $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ ;  $C1 = 0.047\text{ }\mu\text{F}$ ,  $C2\text{--}C4 = 0.33\text{ }\mu\text{F}$  at  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ .

(2) All typical values are at  $V_{CC} = 3.3\text{ V}$  or  $V_{CC} = 5\text{ V}$ , and  $T_A = 25^\circ\text{C}$ .

(3) Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

### Switching Characteristics<sup>(1)</sup>

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)  
 (see [Figure 1](#) and [Figure 2](#))

PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	UNIT
Maximum data rate	$C_L = 1000\text{ pF}$ , $R_L = 3\text{ k}\Omega$ , One DIN switching, See <a href="#">Figure 1</a>	250			kbit/s
	$C_L = 1000\text{ pF}$ , $R_L = 3\text{ k}\Omega$ , $V_{CC} = 4.5\text{ V}$ , One DIN switching, See <a href="#">Figure 1</a>	1000			
	$C_L = 250\text{ pF}$ , $R_L = 3\text{ k}\Omega$ , $V_{CC} = 3\text{ V}$ , One DIN switching, See <a href="#">Figure 1</a>	1000			
$t_{sk(p)}$ Pulse skew <sup>(3)</sup>	$C_L = 150\text{ pF}$ to $2500\text{ pF}$ , $R_L = 3\text{ k}\Omega$ to $7\text{ k}\Omega$ , See <a href="#">Figure 2</a>		25		ns
SR(tr) Slew rate, transition region	$V_{CC} = 3.3\text{ V}$ , $R_L = 3\text{ k}\Omega$ to $7\text{ k}\Omega$ , $C_L = 150\text{ pF}$ to $1000\text{ pF}$ , See <a href="#">Figure 1</a>	24	150		$\text{V}/\mu\text{s}$

(1) Test conditions are  $C1\text{--}C4 = 0.1\text{ }\mu\text{F}$  at  $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ ;  $C1 = 0.047\text{ }\mu\text{F}$ ,  $C2\text{--}C4 = 0.33\text{ }\mu\text{F}$  at  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ .

(2) All typical values are at  $V_{CC} = 3.3\text{ V}$  or  $V_{CC} = 5\text{ V}$ , and  $T_A = 25^\circ\text{C}$ .

(3) Pulse skew is defined as  $|t_{PLH} - t_{PHL}|$  of each channel of the same device.

## ESD Protection

TERMINAL	TEST CONDITIONS			TYP	UNIT
NAME	NO.				
DOUT	13	Human-Body Model		$\pm 15$	kV
		Contact Discharge (IEC61000-4-2)		$\pm 8$	
		Air-Gap Discharge (IEC61000-4-2)		$\pm 8$	

## RECEIVER SECTION

### Electrical Characteristics<sup>(1)</sup>

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 3](#))

PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	UNIT
$V_{OH}$ High-level output voltage	$I_{OH} = -1\text{ mA}$	$V_{CC} = 0.6$	$V_{CC} = 0.1$		V
$V_{OL}$ Low-level output voltage	$I_{OL} = 1.6\text{ mA}$			0.4	V
$V_{IT+}$ Positive-going input threshold voltage	$V_{CC} = 3.3\text{ V}$			1.5	2.4
	$V_{CC} = 5\text{ V}$			1.8	2.4
$V_{IT-}$ Negative-going input threshold voltage	$V_{CC} = 3.3\text{ V}$		0.6	1.2	V
	$V_{CC} = 5\text{ V}$		0.8	1.5	
$V_{hys}$ Input hysteresis ( $V_{IT+} - V_{IT-}$ )				0.5	V
$I_{off}$ Output leakage current				$\pm 0.05$	$\pm 10$
$r_I$ Input resistance	$V_I = \pm 3\text{ V}$ to $\pm 25\text{ V}$	3	5	7	$\text{k}\Omega$

(1) Test conditions are  $C1-C4 = 0.1\text{ }\mu\text{F}$  at  $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ ;  $C1 = 0.047\text{ }\mu\text{F}$ ,  $C2-C4 = 0.33\text{ }\mu\text{F}$  at  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ .

(2) All typical values are at  $V_{CC} = 3.3\text{ V}$  or  $V_{CC} = 5\text{ V}$ , and  $T_A = 25^\circ\text{C}$ .

### Switching Characteristics<sup>(1)</sup>

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	TYP <sup>(2)</sup>	UNIT
$t_{PLH}$ Propagation delay time, low- to high-level output	$C_L = 150\text{ pF}$ , See <a href="#">Figure 3</a>	150	ns
$t_{PHL}$ Propagation delay time, high- to low-level output	$C_L = 150\text{ pF}$ , See <a href="#">Figure 3</a>	150	ns
$t_{sk(p)}$ Pulse skew <sup>(3)</sup>	See <a href="#">Figure 3</a>	50	ns

(1) Test conditions are  $C1-C4 = 0.1\text{ }\mu\text{F}$  at  $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ ;  $C1 = 0.047\text{ }\mu\text{F}$ ,  $C2-C4 = 0.33\text{ }\mu\text{F}$  at  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ .

(2) All typical values are at  $V_{CC} = 3.3\text{ V}$  or  $V_{CC} = 5\text{ V}$ , and  $T_A = 25^\circ\text{C}$ .

(3) Pulse skew is defined as  $|t_{PLH} - t_{PHL}|$  of each channel of the same device.

## ESD Protection

TERMINAL	TEST CONDITIONS		TYP	UNIT
NAME	NO.			
RIN	8	Human-Body Model	$\pm 15$	kV
		Contact Discharge (IEC61000-4-2)	$\pm 8$	
		Air-Gap Discharge (IEC61000-4-2)	$\pm 15$	

## AUTO-POWERDOWN SECTION

### Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 4](#))

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
$V_{T+}(\text{valid})$	Receiver input threshold for $\text{INVALID}$ high-level output voltage FORCEON = GND, $\overline{\text{FORCEOFF}} = V_{CC}$		2.7	V
$V_{T-}(\text{valid})$	Receiver input threshold for $\text{INVALID}$ high-level output voltage FORCEON = GND, $\overline{\text{FORCEOFF}} = V_{CC}$		-2.7	V
$V_{T}(\text{invalid})$	Receiver input threshold for $\text{INVALID}$ low-level output voltage FORCEON = GND, $\overline{\text{FORCEOFF}} = V_{CC}$	-0.3	0.3	V
$V_{OH}$	$\text{INVALID}$ , READY output voltage high $I_{OH} = -1\text{ mA}$ , FORCEON = GND, $\overline{\text{FORCEOFF}} = V_{CC}$	$V_{CC} - 0.6$		V
$V_{OL}$	$\text{INVALID}$ , READY output voltage low $I_{OL} = 1.6\text{ mA}$ , FORCEON = GND, $\overline{\text{FORCEOFF}} = V_{CC}$		0.4	V

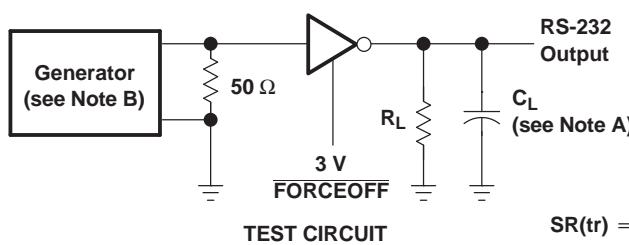
### Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 4](#))

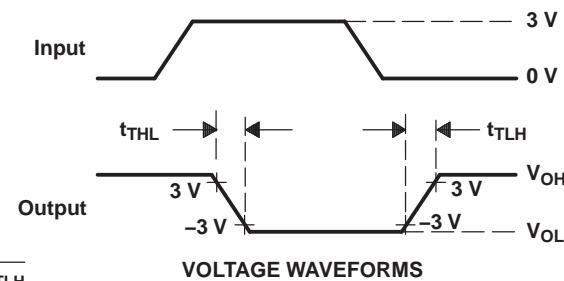
PARAMETER	MIN	TYP <sup>(1)</sup>	MAX	UNIT
$t_{INVH}$	Propagation delay time, low- to high-level output	1		$\mu\text{s}$
$t_{INVL}$	Propagation delay time, high- to low-level output	30		$\mu\text{s}$
$t_{WU}$	Supply enable time	100		$\mu\text{s}$
$t_{AUTOPRDN}$	Driver or receiver edge to driver's shutdown	$V_{CC} = 5\text{ V}$	15 30 60	s

(1) All typical values are at  $V_{CC} = 3.3\text{ V}$  or  $V_{CC} = 5\text{ V}$ , and  $T_A = 25^\circ\text{C}$ .

## PARAMETER MEASUREMENT INFORMATION



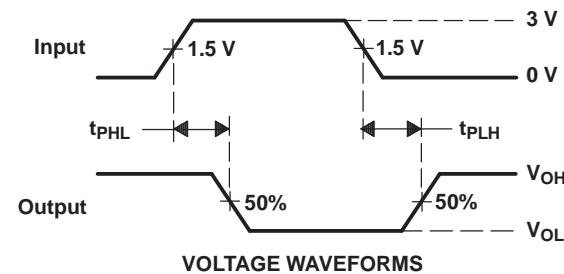
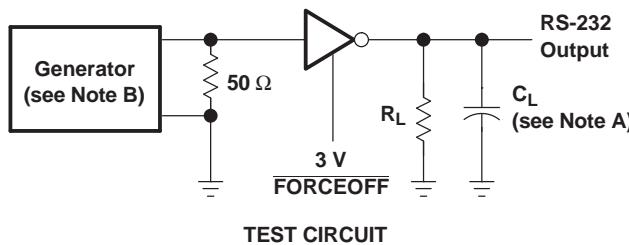
$$SR(tr) = \frac{6 \text{ V}}{t_{THL} \text{ or } t_{TLH}}$$



NOTES: A.  $C_L$  includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \leq 10$  ns,  $t_f \leq 10$  ns.

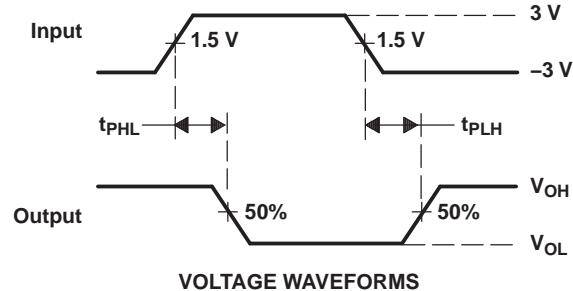
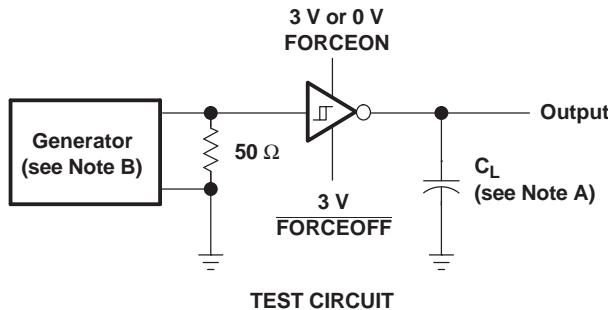
Figure 1. Driver Slew Rate



NOTES: A.  $C_L$  includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \leq 10$  ns,  $t_f \leq 10$  ns.

Figure 2. Driver Pulse Skew

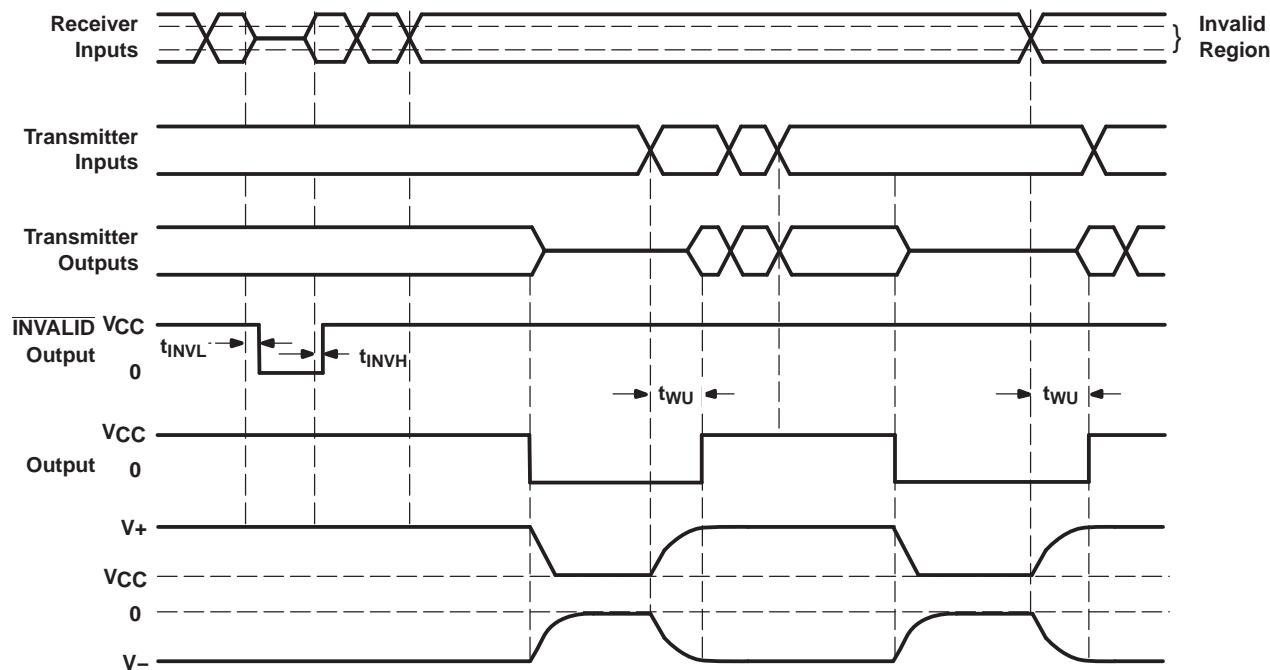


NOTES: A.  $C_L$  includes probe and jig capacitance.

B. The pulse generator has the following characteristics:  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \leq 10$  ns,  $t_f \leq 10$  ns.

Figure 3. Receiver Propagation Delay Times

PARAMETER MEASUREMENT INFORMATION (continued)



VOLTAGE WAVEFORMS

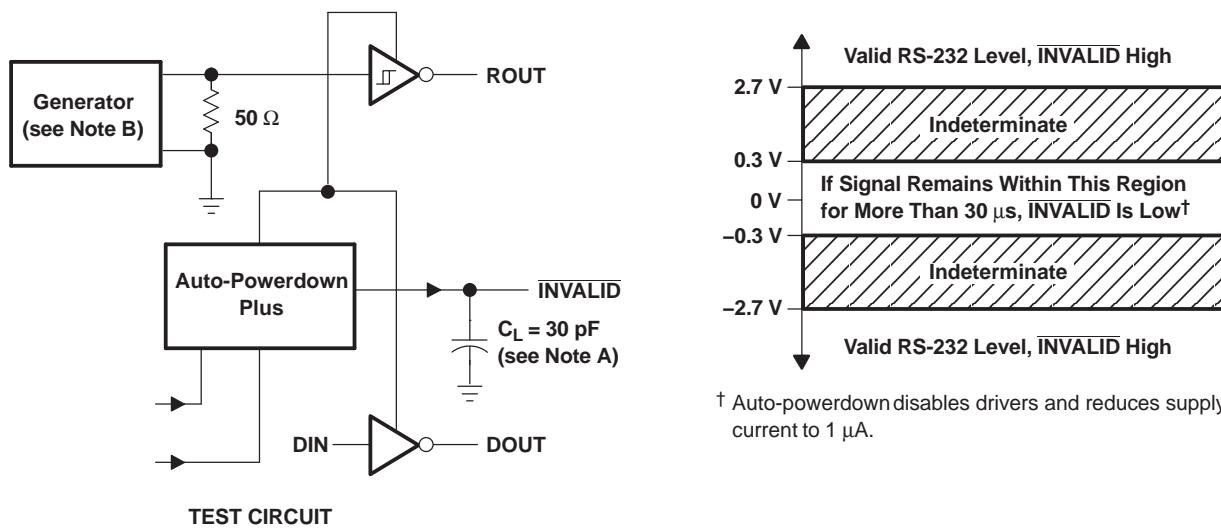
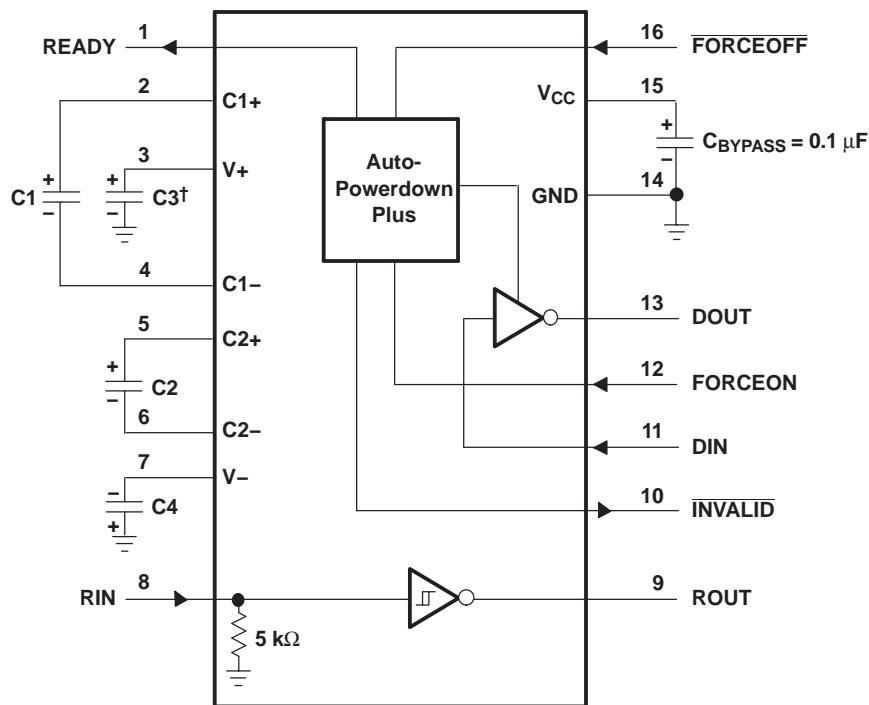


Figure 4. INVALID Propagation Delay Times and Driver Enabling Time

## APPLICATION INFORMATION



† C3 can be connected to V<sub>CC</sub> or GND.

NOTES: A. Resistor values shown are nominal.  
B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

V<sub>CC</sub> vs CAPACITOR VALUES

V <sub>CC</sub>	C1	C2, C3, and C4
3.3 V $\pm 0.3$ V	0.1 $\mu\text{F}$	0.1 $\mu\text{F}$
5 V $\pm 0.5$ V	0.047 $\mu\text{F}$	0.33 $\mu\text{F}$
3 V to 5.5 V	0.1 $\mu\text{F}$	0.47 $\mu\text{F}$

Figure 5. Typical Operating Circuit and Capacitor Values

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TRS3227CDBR	ACTIVE	SSOP	DB	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	RS27C	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
TRS3227IDB	ACTIVE	SSOP	DB	16	80	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	RS27I	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
TRS3227IDBR	ACTIVE	SSOP	DB	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	RS27I	<span style="background-color: red; color: white; padding: 2px;">Samples</span>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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## PACKAGE OPTION ADDENDUM

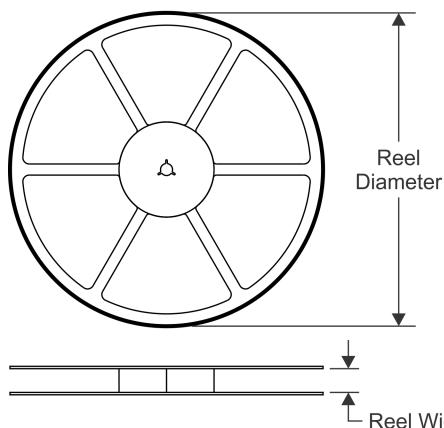
10-Dec-2020

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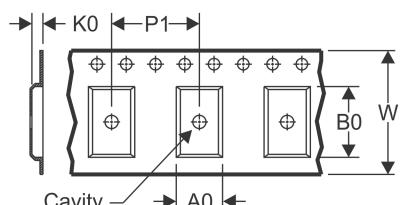
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

## TAPE AND REEL INFORMATION

## REEL DIMENSIONS

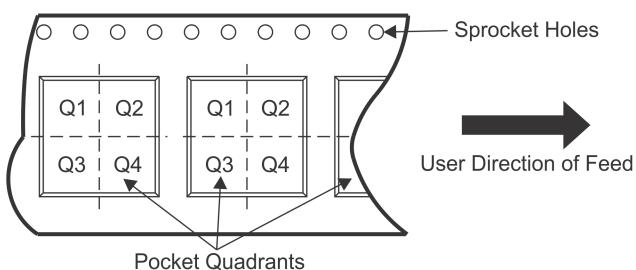


## TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



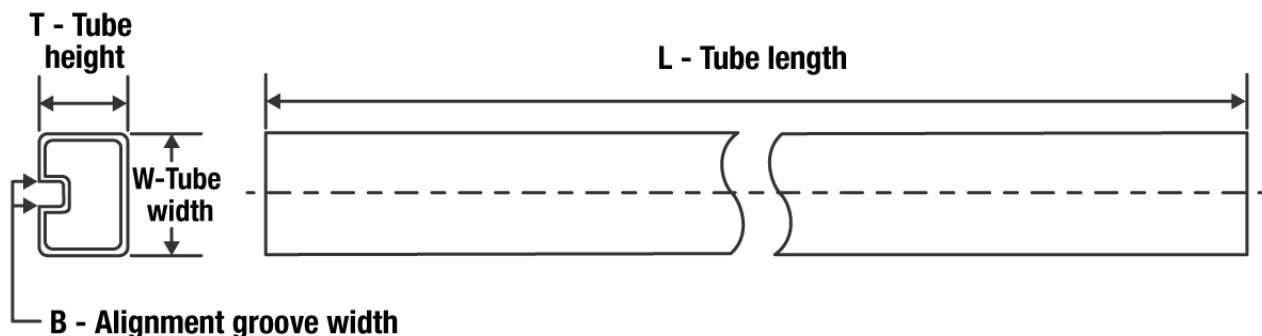
\*All dimensions are nominal

All dimensions are nominal														
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant		
TRS3227CDBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1		
TRSS3227IDBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1		

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TRS3227CDBR	SSOP	DB	16	2000	853.0	449.0	35.0
TRS3227IDBR	SSOP	DB	16	2000	853.0	449.0	35.0

**TUBE**


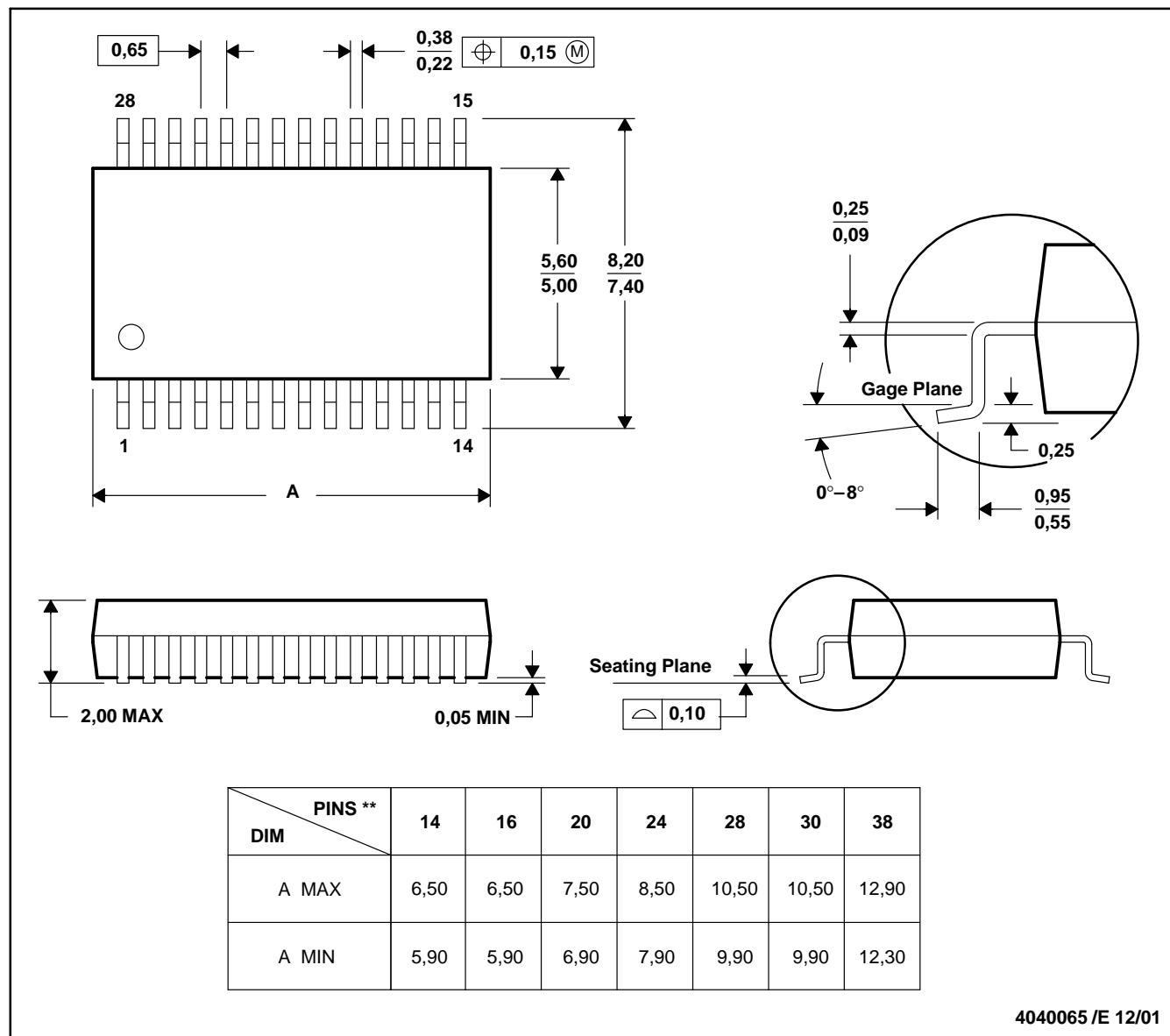
\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
TRS3227IDB	DB	SSOP	16	80	530	10.5	4000	4.1

## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

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